APLUS TECHNOLOGY

DDRIII SDRAM 1866 204-PIN SO_DIMM Industrial 8GB 512Mx8

DESCRIPTION:

This document describes Aplus 1GB x 64-bit 8GB DDR3 SDRAM (Synchronous DRAM) Dual In-Line Memory Module. The components on this module include sixteen 512M x 8-bit DDR3 SDRAMs in FBGA packages and a 2048-bit serial EEPROM. Those components were mounted on a 204-pin printed circuit board. This 204-pin SO_DIMM is used to be mounted into 204-pin edge connector sockets and data I/O transactions could be apply on both edges of DQS. The electrical and mechanical specifications are as follows:

FEATURES:

Extra-thick 30µ gold-plated contact PINS
RoHS compliant products
JEDEC standard 1.5V ± 0.075V power supply
1.5V ± 0.075V power supply VDDQ
3.0V to 3.6V VDDSPD
Industrial grade capacitors ensure voltage stability
Stable operation in extreme temperature -40℃ to +95℃
Fast data transfer rates: PC3-14900
Nominal and dynamic on-die termination (ODT) for data strobe and mask signals
Single Rank
On-board IIC temperature sensor with integrated serial presence-detect (SPD) EEPROM
8 inter selectable burst chop BC4 and burst length BL8 on- the-fly (OTF)
Terminated control, command, and address bus
100% tested for performance and reliability

DDR3 DRAM Speed

DDR3-1866 1866Mbps CL-tRCD-tRP 13-13-13

PERFORMANCE:

Clock Cycle Time (tCK) CL(1) 933
Row Cycle Time (tRC) 47.125ns for 1866
REFRESH Row Cycle Time (tRCD) 13.125ns
Memory Clock/Data Rate: 1.07ns/1866MT/s
Operating Case temperature range: Industrial -40℃ <=TC<= +95℃

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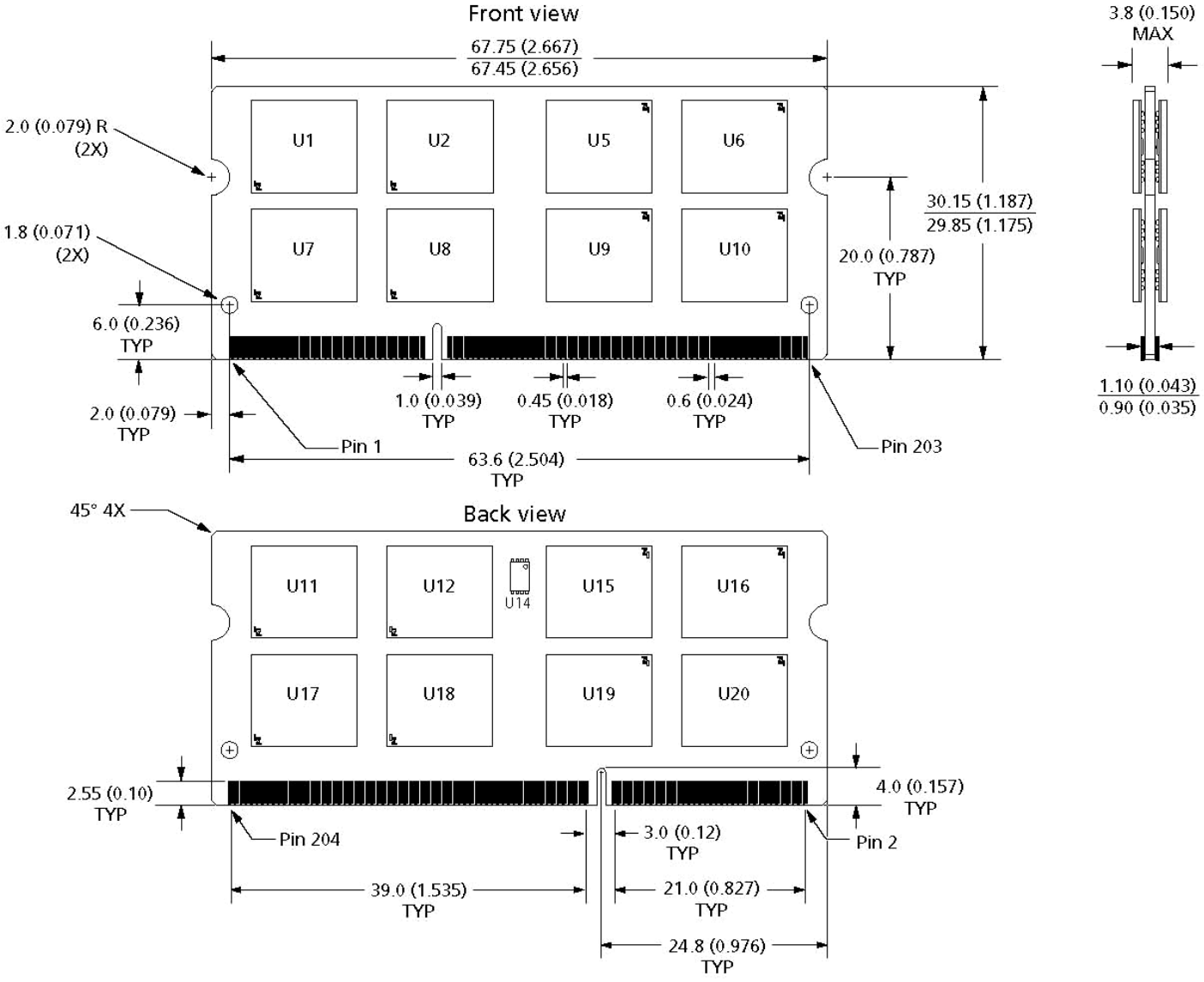
Operating Temperature **-40℃ to +95℃**

Storage Temperature **-55℃ to +100℃**



Notes:
1. All dimensions are in millimeters (inches); MAX/MIN or typical (TYP) where noted.
2. The dimensional diagram is for reference only.

PCB: 30μ